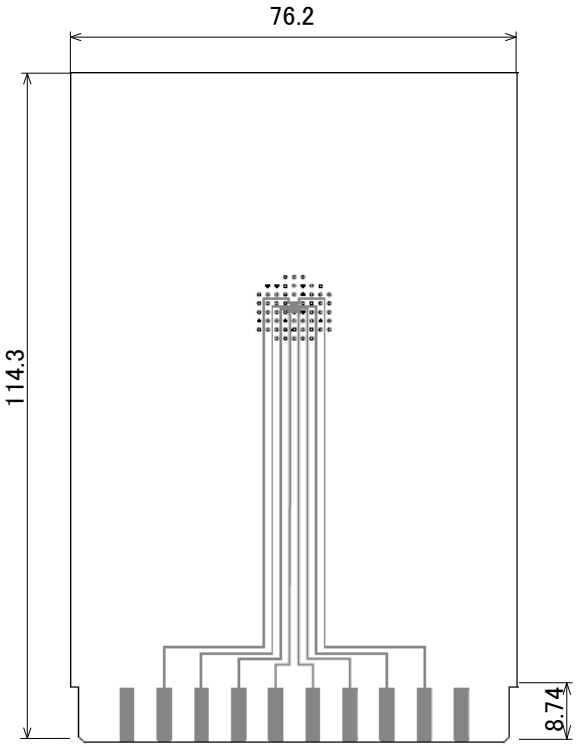
●USP-8B06(DAF) Power Dissipation

Power dissipation data for the USP-8B06 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.



1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: 76.2mm × 114.3mm（8700mm^2 in one side）

1st inner layer：50mm × 50mm_with heat sink

2nd inner layer：70mm × 70mm_with heat sink

3rd inner layer：70mm × 70mm_ with heat sink

4th inner layer：50mm × 50mm_with heat sink

Material: Glass Epoxy (FR-4)

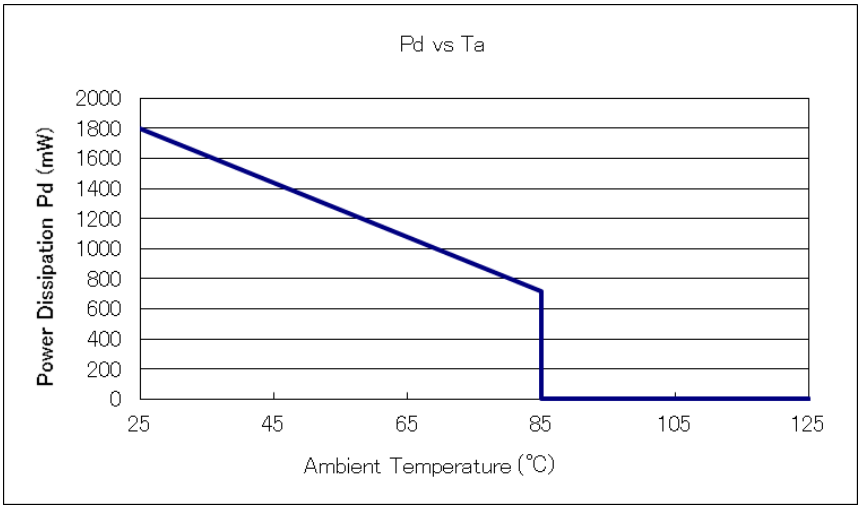
Thickness: 1.6mm

Through-hole: 60 × ϕ 0.2mm

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	θa(℃/W)
25	1800	55.56
85	720	



●USP-8B06 Power Dissipation (JESD51-7)

Power dissipation data for the USP-8B06 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: 76.2mm × 114.3mm（8700mm^2 in one side）

1st inner layer：No copper foil

Package heat-sink is tied to the copper traces

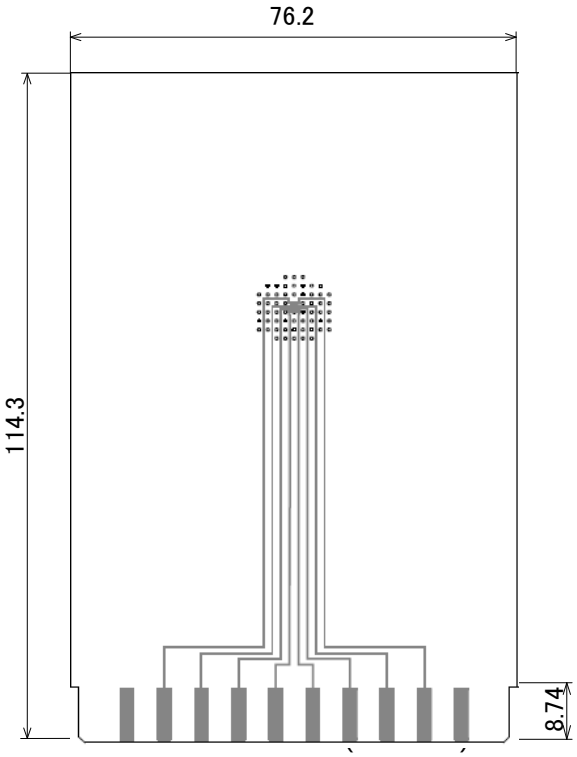
2nd inner layer：70mm × 70mm_with heat sink

3rd inner layer：70mm × 70mm_ with heat sink

4th inner layer：No copper foil

Each heat sink back metal is connected to the

Inner layers respectively.



Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole: 60 × φ0.2mm

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	θja(℃/W)
25	1240	80.65
105	248